



Material Content Data Sheet



Sales Product Name	TLE7242-2G			Issued	19. July 2018			
MA#	MA001140264							
Package	PG-DSO-28-42			Weight*	824.63 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	22.000	2.67	2.67	26678	26678
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		83	
	non noble metal	zinc	7440-66-6	0.275	0.03		333	
	non noble metal	iron	7439-89-6	5.500	0.67		6669	
wire	non noble metal	copper	7440-50-8	223.311	27.08	27.79	270802	277887
	non noble metal	copper	7440-50-8	0.429	0.05	0.05	521	521
	encapsulation	organic material	carbon black	1333-86-4	1.124	0.14		1363
encapsulation	plastics	epoxy resin	-	51.712	6.27		62709	
	inorganic material	silicondioxide	60676-86-0	509.248	61.75	68.16	617550	681622
leadfinish	non noble metal	tin	7440-31-5	4.913	0.60	0.60	5958	5958
plating	noble metal	silver	7440-22-4	1.047	0.13	0.13	1270	1270
glue	plastics	epoxy resin	-	1.250	0.15		1516	
	noble metal	silver	7440-22-4	3.750	0.45	0.60	4548	6064
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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